

# STARPOWER

SEMICONDUCTOR

**IGBT**

## GD300FFY65P3H

**650V/300A 6 in one-package**

### General Description

STARPOWER IGBT Power Module provides ultra low conduction loss as well as short circuit ruggedness. They are designed for the applications such as hybrid and electric vehicles.



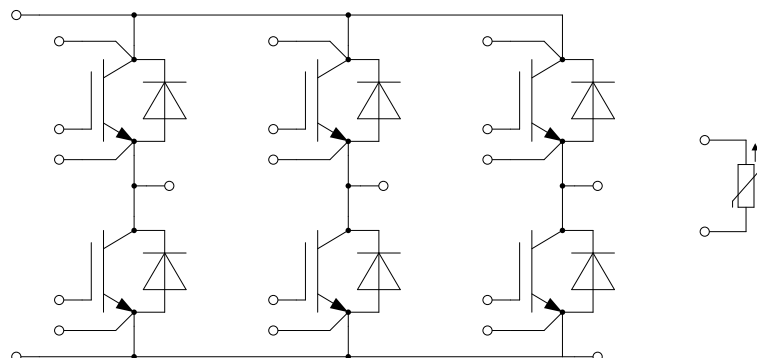
### Features

- Low  $V_{CE(sat)}$  Trench IGBT technology
- 6 $\mu$ s short circuit capability
- $V_{CE(sat)}$  with positive temperature coefficient
- Maximum junction temperature 175°C
- Low inductance case
- Fast & soft reverse recovery anti-parallel FWD
- Isolated copper pinfin baseplate using DBC technology

### Typical Applications

- Automotive application
- Hybrid and electric vehicle
- Inverter for motor drive

### Equivalent Circuit Schematic



**Absolute Maximum Ratings**  $T_C=25^{\circ}\text{C}$  unless otherwise noted**IGBT**

Symbol	Description	Value	Unit
$V_{CES}$	Collector-Emitter Voltage	650	V
$V_{GES}$	Gate-Emitter Voltage	$\pm 20$	V
$I_C$	Collector Current @ $T_C=25^{\circ}\text{C}$	349	A
	@ $T_C=50^{\circ}\text{C}$	300	A
$I_{CM}$	Pulsed Collector Current $t_p=1\text{ms}$	600	A
$P_D$	Maximum Power Dissipation @ $T_j=175^{\circ}\text{C}$	842	W

**Diode**

Symbol	Description	Value	Unit
$V_{RRM}$	Repetitive Peak Reverse Voltage	650	V
$I_F$	Diode Continuous Forward Current	300	A
$I_{FM}$	Diode Maximum Forward Current $t_p=1\text{ms}$	600	A

**Module**

Symbol	Description	Value	Unit
$T_{jmax}$	Maximum Junction Temperature	175	$^{\circ}\text{C}$
$T_{jop}$	Operating Junction Temperature	-40 to +150	$^{\circ}\text{C}$
$T_{STG}$	Storage Temperature Range	-40 to +125	$^{\circ}\text{C}$
$V_{ISO}$	Isolation Voltage RMS, $f=50\text{Hz}$ , $t=1\text{min}$	2500	V

**IGBT Characteristics**  $T_C=25^\circ\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_{CE(sat)}$	Collector to Emitter Saturation Voltage	$I_C=300\text{A}, V_{GE}=15\text{V}, T_j=25^\circ\text{C}$		1.45	1.90	V
		$I_C=300\text{A}, V_{GE}=15\text{V}, T_j=125^\circ\text{C}$		1.60		
		$I_C=300\text{A}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}$		1.70		
$V_{GE(th)}$	Gate-Emitter Threshold Voltage	$I_C=4.8\text{mA}, V_{CE}=V_{GE}, T_j=25^\circ\text{C}$	5.1	5.8	6.4	V
$I_{CES}$	Collector Cut-Off Current	$V_{CE}=V_{CES}, V_{GE}=0\text{V}, T_j=25^\circ\text{C}$			5.0	mA
$I_{GES}$	Gate-Emitter Leakage Current	$V_{GE}=V_{GES}, V_{CE}=0\text{V}, T_j=25^\circ\text{C}$			400	nA
$R_{Gint}$	Internal Gate Resistance			1.0		$\Omega$
$C_{ies}$	Input Capacitance	$V_{CE}=25\text{V}, f=1\text{MHz}, V_{GE}=0\text{V}$		18.5		nF
$C_{res}$	Reverse Transfer Capacitance			0.55		nF
$Q_G$	Gate Charge	$V_{GE}=-15\text{V}\dots+15\text{V}$		3.20		$\mu\text{C}$
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=300\text{A}, R_G=2.4\Omega, V_{GE}=\pm 15\text{V}, T_j=25^\circ\text{C}$		88		ns
$t_r$	Rise Time			39		ns
$t_{d(off)}$	Turn-Off Delay Time			391		ns
$t_f$	Fall Time			39		ns
$E_{on}$	Turn-On Switching Loss			1.69		mJ
$E_{off}$	Turn-Off Switching Loss			7.87		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=300\text{A}, R_G=2.4\Omega, V_{GE}=\pm 15\text{V}, T_j=125^\circ\text{C}$		95		ns
$t_r$	Rise Time			48		ns
$t_{d(off)}$	Turn-Off Delay Time			415		ns
$t_f$	Fall Time			55		ns
$E_{on}$	Turn-On Switching Loss			2.40		mJ
$E_{off}$	Turn-Off Switching Loss			9.68		mJ
$t_{d(on)}$	Turn-On Delay Time	$V_{CC}=300\text{V}, I_C=300\text{A}, R_G=2.4\Omega, V_{GE}=\pm 15\text{V}, T_j=150^\circ\text{C}$		103		ns
$t_r$	Rise Time			48		ns
$t_{d(off)}$	Turn-Off Delay Time			424		ns
$t_f$	Fall Time			55		ns
$E_{on}$	Turn-On Switching Loss			2.56		mJ
$E_{off}$	Turn-Off Switching Loss			10.08		mJ
$I_{SC}$	SC Data	$t_p \leq 6\mu\text{s}, V_{GE}=15\text{V}, T_j=150^\circ\text{C}, V_{CC}=360\text{V}, V_{CEM} \leq 650\text{V}$		1500		A

**Diode Characteristics**  $T_C=25^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$V_F$	Diode Forward Voltage	$I_F=300\text{A}, V_{GE}=0\text{V}, T_j=25^{\circ}\text{C}$		1.55	2.00	V
		$I_F=300\text{A}, V_{GE}=0\text{V}, T_j=125^{\circ}\text{C}$		1.50		
		$I_F=300\text{A}, V_{GE}=0\text{V}, T_j=150^{\circ}\text{C}$		1.45		
$Q_r$	Recovered Charge	$V_R=300\text{V}, I_F=300\text{A},$ $-di/dt=7150\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=25^{\circ}\text{C}$		14.1		$\mu\text{C}$
$I_{RM}$	Peak Reverse Recovery Current			207		A
$E_{rec}$	Reverse Recovery Energy			3.75		mJ
$Q_r$	Recovered Charge	$V_R=300\text{V}, I_F=300\text{A},$ $-di/dt=7150\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=125^{\circ}\text{C}$		26.5		$\mu\text{C}$
$I_{RM}$	Peak Reverse Recovery Current			259		A
$E_{rec}$	Reverse Recovery Energy			6.80		mJ
$Q_r$	Recovered Charge	$V_R=300\text{V}, I_F=300\text{A},$ $-di/dt=7150\text{A}/\mu\text{s}, V_{GE}=-15\text{V}$ $T_j=150^{\circ}\text{C}$		30.6		$\mu\text{C}$
$I_{RM}$	Peak Reverse Recovery Current			273		A
$E_{rec}$	Reverse Recovery Energy			7.70		mJ

**NTC Characteristics**  $T_C=25^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Test Conditions	Min.	Typ.	Max.	Unit
$R_{25}$	Rated Resistance			5.0		$\text{k}\Omega$
$\Delta R/R$	Deviation of $R_{100}$	$T_C=100^{\circ}\text{C}, R_{100}=493.3\Omega$	-5		5	%
$P_{25}$	Power Dissipation				20.0	mW
$B_{25/50}$	B-value	$R_2=R_{25}\exp[B_{25/50}(1/T_2-1/(298.15\text{K}))]$		3375		K
$B_{25/80}$	B-value	$R_2=R_{25}\exp[B_{25/80}(1/T_2-1/(298.15\text{K}))]$		3411		K
$B_{25/100}$	B-value	$R_2=R_{25}\exp[B_{25/100}(1/T_2-1/(298.15\text{K}))]$		3433		K

**Module Characteristics**  $T_F=25^{\circ}\text{C}$  unless otherwise noted

Symbol	Parameter	Min.	Typ.	Max.	Unit
$\Delta p$	Pressure Drop Cooling Circuit $\Delta V/\Delta t=10.0\text{dm}^3/\text{min}; T_F=25^{\circ}\text{C};$ Cooling Fluid=50% Water/50% Ethylene Glycol		50		mbar
p	Maximum Pressure In Cooling Circuit			2.0	bar
$L_{CE}$	Stray Inductance		30		nH
$R_{CC'+EE'}$	Module Lead Resistance, Terminal to Chip		1.00		m $\Omega$
$R_{thJF}$	Junction-to-Cooling Fluid (per IGBT) Junction-to-Cooling Fluid (per Diode)			0.179 0.290	K/W
M	Terminal Connection Torque, Screw M6 Mounting Torque, Screw M5	3.0 3.0		6.0 6.0	N.m
G	Weight of Module		665		g

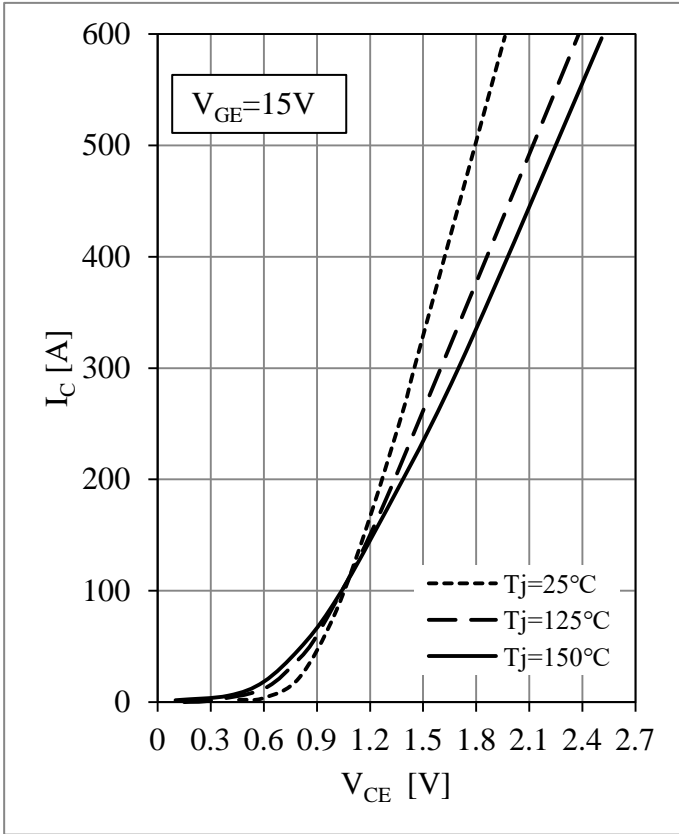


Fig 1. IGBT Output Characteristics

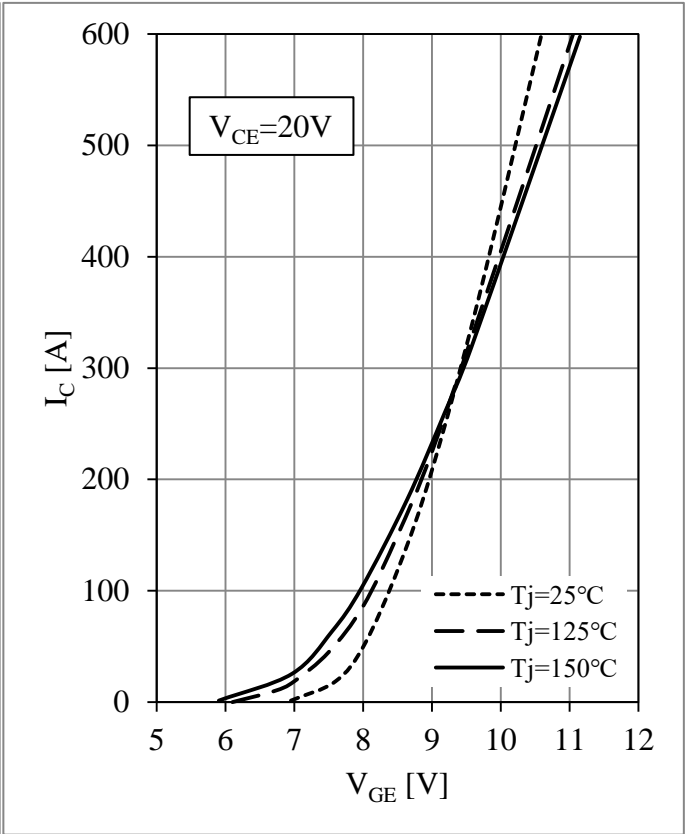


Fig 2. IGBT Transfer Characteristics

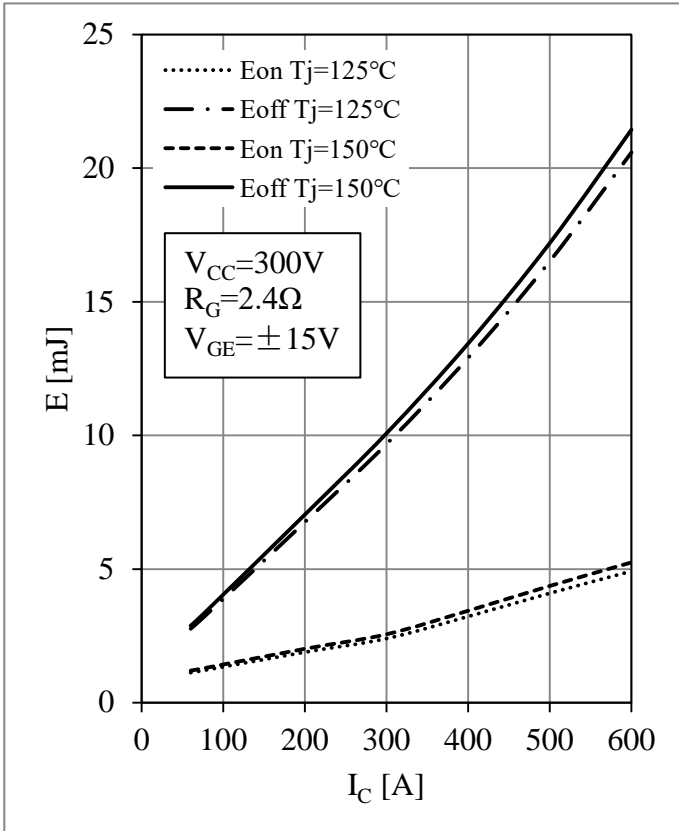


Fig 3. IGBT Switching Loss vs.  $I_c$

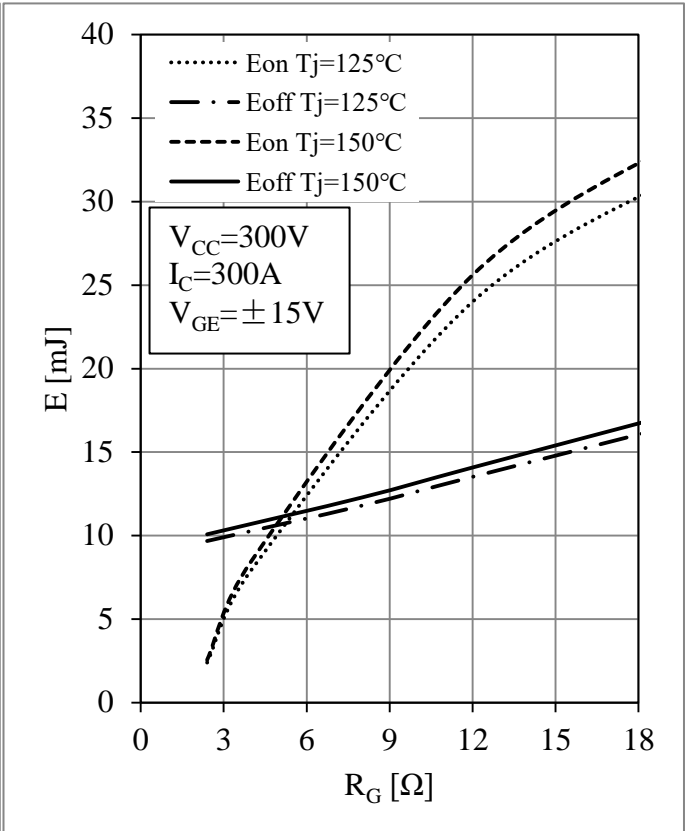


Fig 4. IGBT Switching Loss vs.  $R_g$

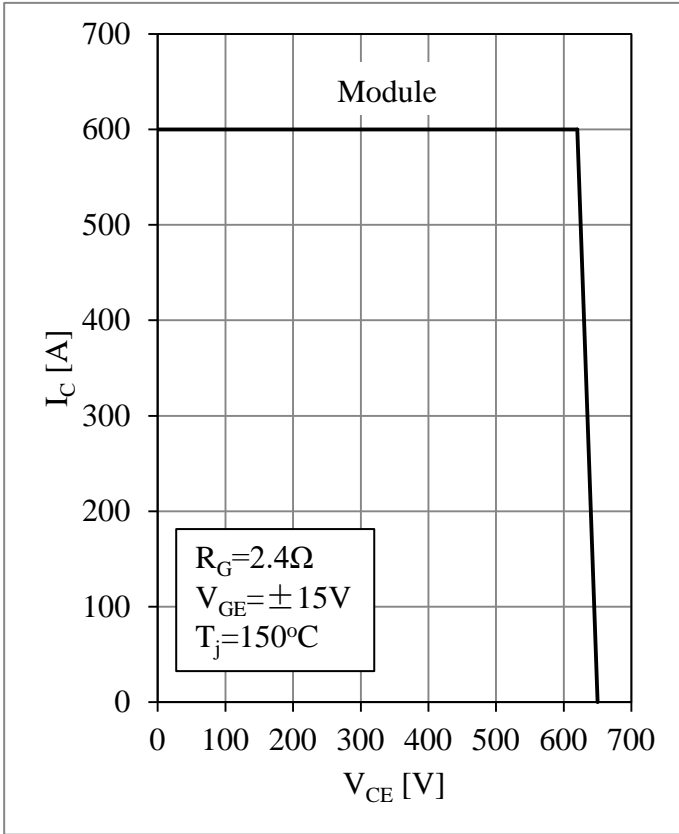


Fig 5. RBSOA

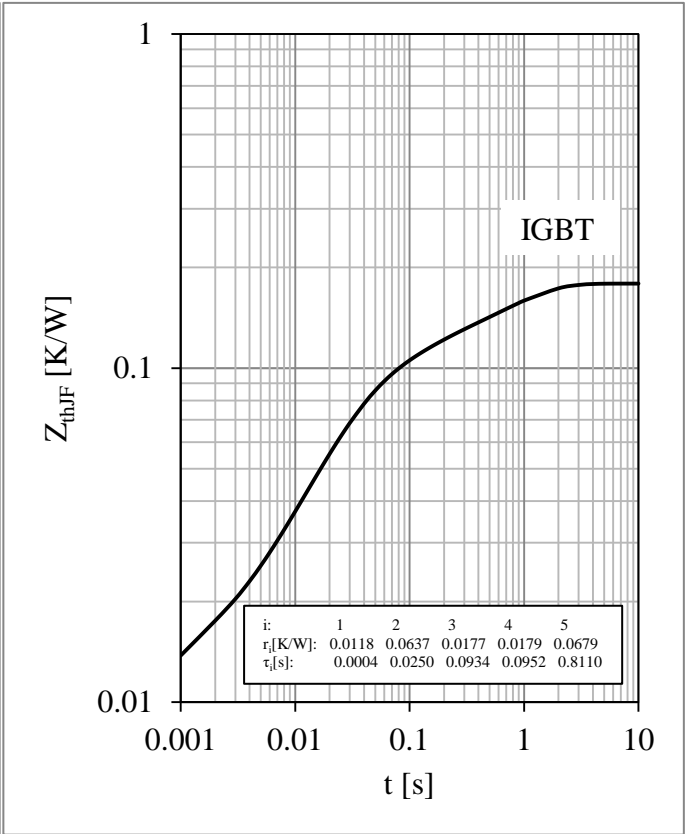


Fig 6. IGBT Transient Thermal Impedance

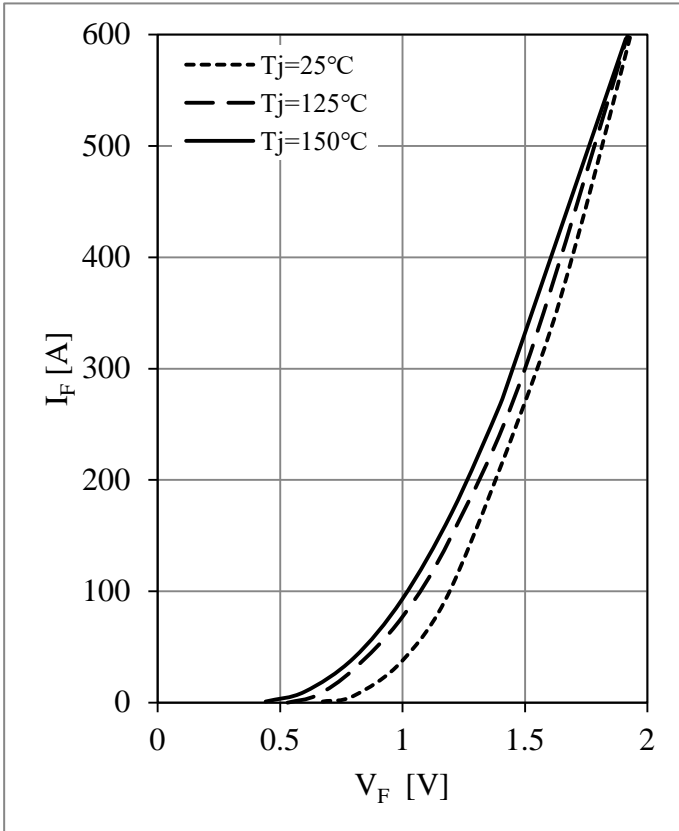


Fig 7. Diode Forward Characteristics

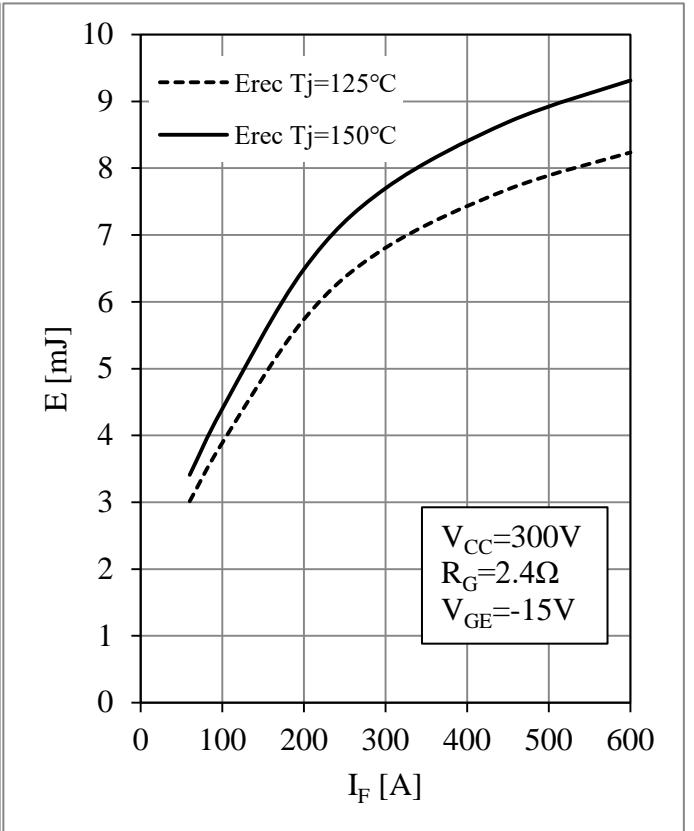


Fig 8. Diode Switching Loss vs.  $I_F$

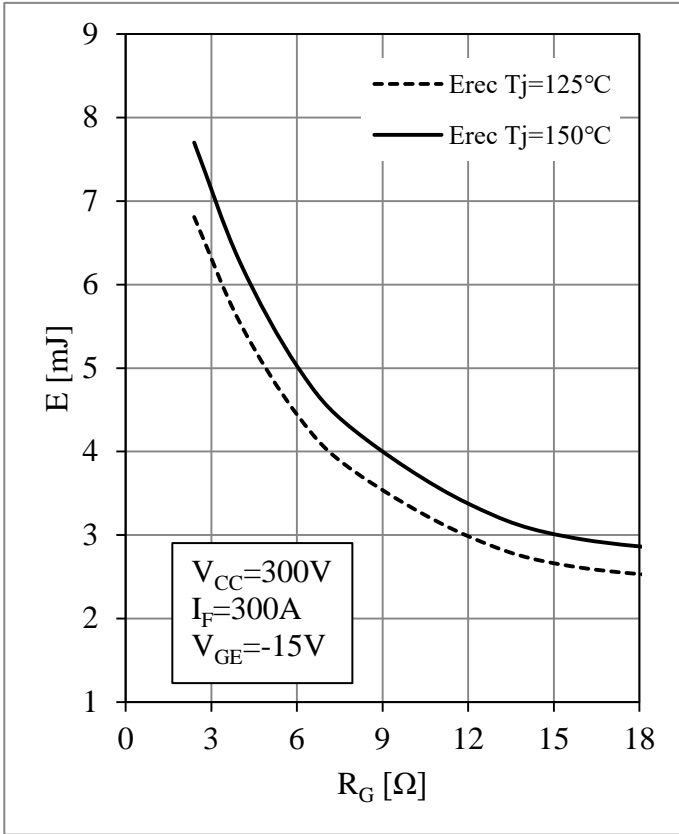


Fig 9. Diode Switching Loss vs.  $R_G$

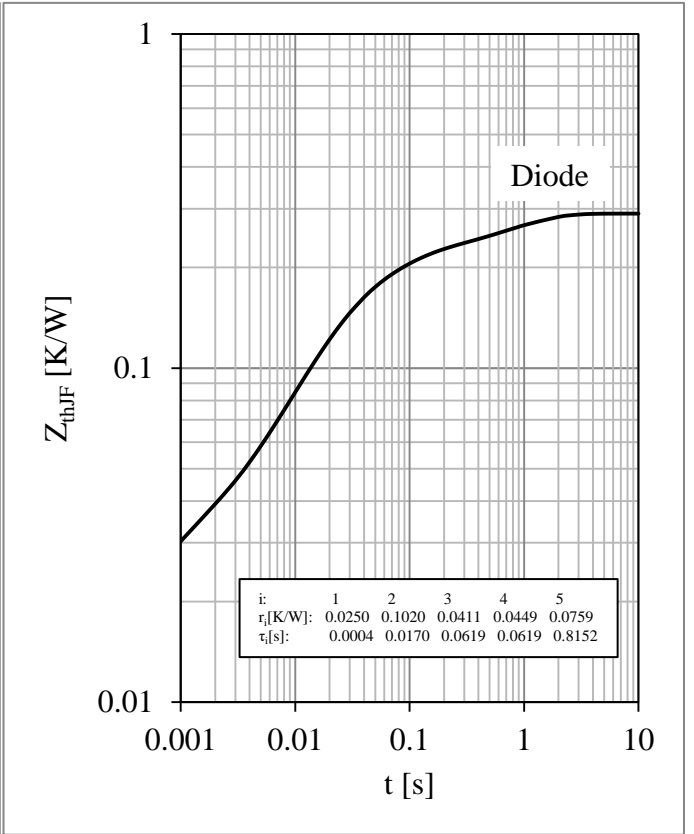


Fig 10. Diode Transient Thermal Impedance

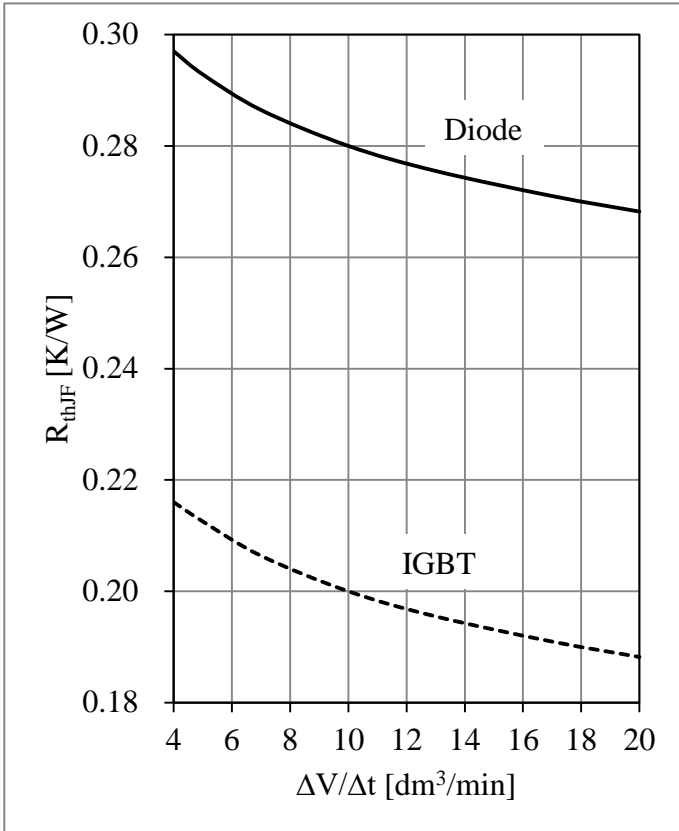


Fig 11. Thermal Impedance

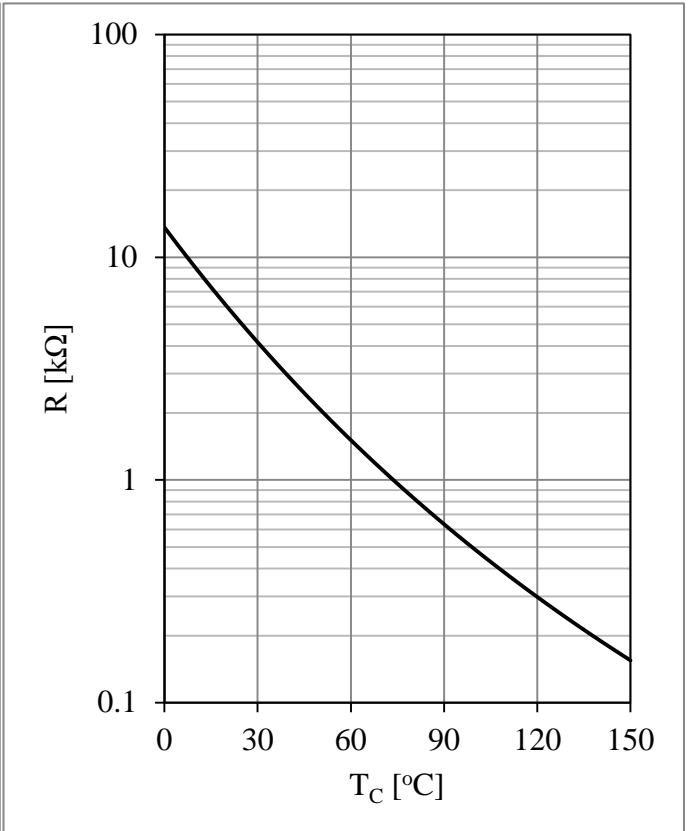
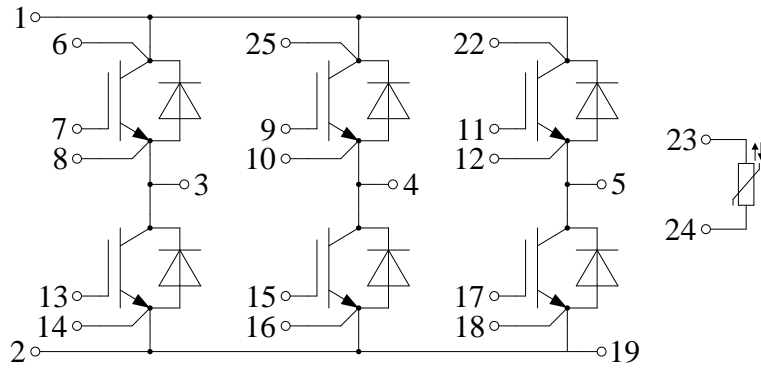


Fig 11. NTC Temperature Characteristic

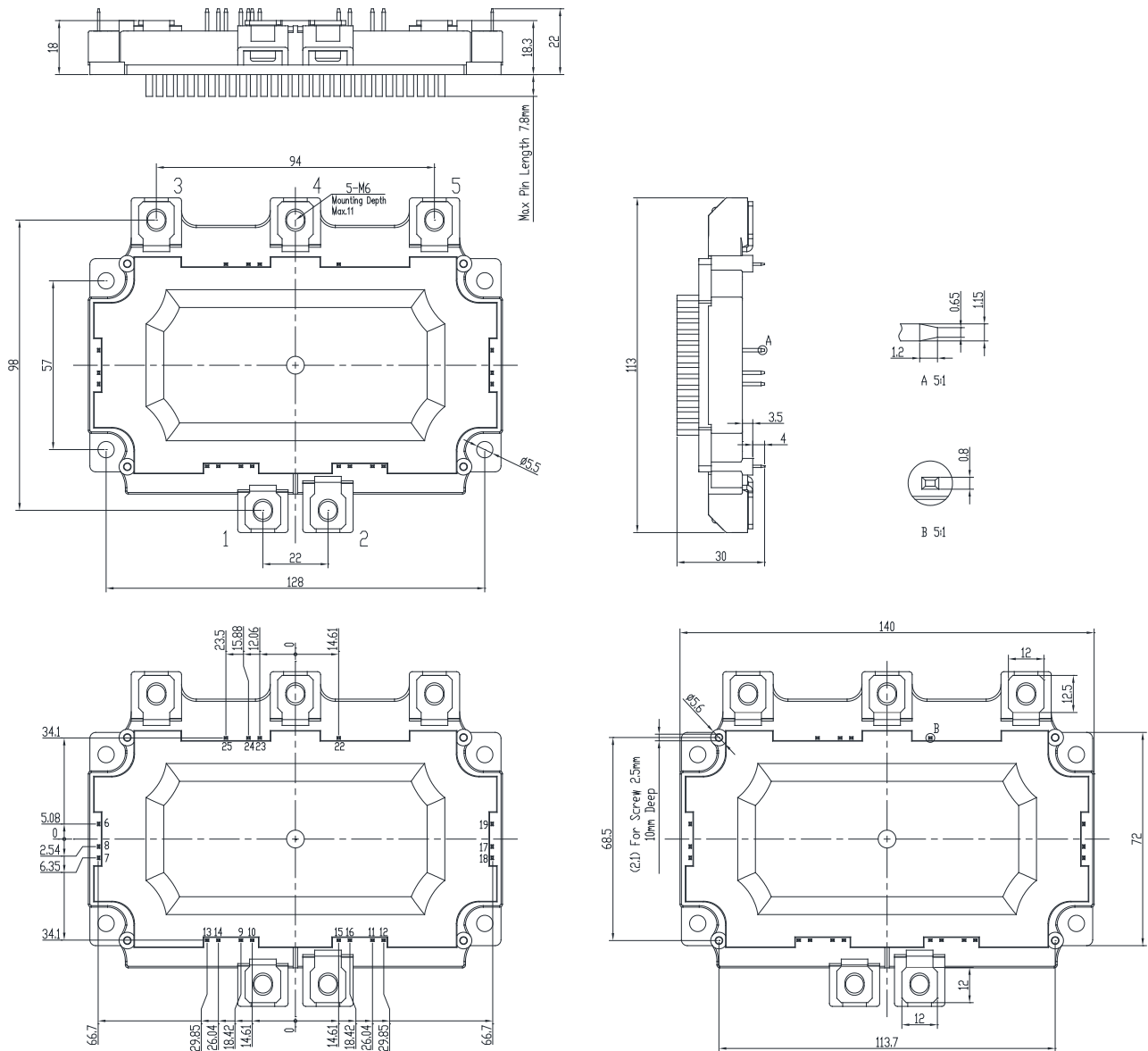


**Circuit Schematic**



**Package Dimensions**

Dimensions in Millimeters



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